

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 1.586001**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.005851	1000000	3689.15258789		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.458357	975000	289001.71875		
		Iron (Fe)	7439-89-6	0.011283	24000	7114.11865234		
		Phosphorus (P)	7723-14-0	0.000141	300	88.9028396606		
		Zinc (Zn)	7440-66-6	0.000329	700	207.439971924		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.470110</b>	<b>1000000</b>	<b>296412.15625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.037246	1000000	23484.2324219		
		<b>External Plating Total:</b>				<b>0.037246</b>	<b>1000000</b>	<b>23484.2324219</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.003761	1000000	2371.37280273		
<b>Internal Plating Total:</b>				<b>0.003761</b>	<b>1000000</b>	<b>2371.37280273</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001482	750000	934.425598145		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000494	250000	311.475189209		
<b>Die Attach Total:</b>				<b>0.001976</b>	<b>1000000</b>	<b>1245.90075684</b>		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.143937	135000	90754.671875		
		Bromine (Br)	40039-93-8	0.007463	7000	4705.54541016		
		Silica (SiO2)	60676-86-0	0.895608	840000	564695.6875		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.013861	13000	8739.59082031		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.005331	5000	3361.28393555		
		<b>Encapsulation Total:</b>				<b>1.066200</b>	<b>1000000</b>	<b>672256.8125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000857	1000000	540.352722168		
					<b>TOTAL MASS (g) :</b>	<b>1.586001</b>		